



Material Content Data Sheet



Sales Product Name		IDD04SG60C		Issued		29. August 2013		
MA#		MA000809444						
Package		PG-TO252-3-311		Weight*		311.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.047	0.01		150	
	non noble metal	tin	7440-31-5	0.012	0.00		39	
	inorganic material	silicon	7440-21-3	0.593	0.19	0.20	1902	2091
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.049	0.02		156	
	non noble metal	copper	7440-50-8	162.275	52.05	52.12	520458	521134
wire	non noble metal	aluminium	7429-90-5	0.118	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	1.447	0.46		4641	
	plastics	epoxy resin	-	25.324	8.12		81221	
	inorganic material	silicondioxide	60676-86-0	117.939	37.83	46.41	378260	464123
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11995	11995
plating	non noble metal	nickel	7440-02-0	0.086	0.03		277	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	278
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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